

DUAL N-CHANNEL 450V - 4.1Ω - 0.4A SO-8 SuperMESH™ POWER MOSFET

TYPE	V_{DSS}	R _{DS(on)}	ID
STS1DNC45	450 V	< 4.5 Ω	0.4 A

- TYPICAL $R_{DS}(on) = 4.1\Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- GATE CHARGE MINIMIZED

DESCRIPTION

The SuperMESH[™] series is obtained through an extreme optimization of ST's well established stripbased PowerMESH[™] layout. In addition to pushing on-resistance significantly down, special care is taken to ensure a very good dv/dt capability for the most demanding applications. Such series complements ST full range of high voltage MOSFETs including revolutionary MDmesh[™] products.

APPLICATIONS

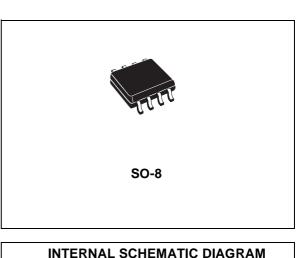
- SWITCH MODE LOW POWER SUPPLIES (SMPS)
- DC-DC CONVERTERS
- LOW POWER, LOW COST CFL (COMPACT FLUORESCENT LAMPS)
- LOW POWER BATTERY CHARGERS

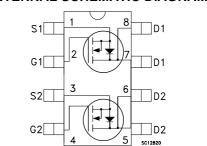
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	450	V
V _{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	450	V
V_{GS}	Gate- source Voltage	± 30	V
Ι _D	Drain Current (continuous) at $T_C = 25^{\circ}C$ Drain Current (continuous) at $T_C = 100^{\circ}C$	0.40 0.25	A A
$I_{DM}\left(\bullet ight)$	Drain Current (pulsed)	1.6	Α
P _{TOT}	Total Dissipation at $T_C = 25^{\circ}C$ Dual Operation Total Dissipation at $T_C = 25^{\circ}C$ Single Operation	1.6 2	W W
dv/dt(1)	Peak Diode Recovery voltage slope	3	V/ns

(•) Pulse width limited by safe operating area

(1) $I_{SD} \le 0.4$ A, di/dt ≤ 100 A/µs, $V_{DD} \le V_{(BR)DSS}$, $T_j \le T_{JMAX}$.





THERMAL DATA

Rthj-amb(#)	Thermal Resistance Junction-ambient Max Single Operation Thermal Resistance Junction-ambient Max Dual Operation	62.5 78	°C/W °C/W
Tj	Max. Operating Junction Temperature	150	°C
T _{stg}	Storage Temperature	–65 to 150	°C

(#) When Mounted on FR4 board (Steady State)

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max)	0.4	A
E _{AS}	Single Pulse Avalanche Energy (starting $T_j = 25 \text{ °C}, I_D = I_{AR}, V_{DD} = 50 \text{ V}$)	30	mJ

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	450			V
I _{DSS}	Zero Gate Voltage	V _{DS} = Max Rating			1	μA
	Drain Current (V _{GS} = 0)	V_{DS} = Max Rating, T_{C} = 125 °C			50	μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 30V$			±100	nA

ON (1)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.3	3	3.7	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V, I _D = 0.5 A		4.1	4.5	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (1)	Forward Transconductance	$V_{DS} = 25 V, I_D = 0.5 A$		1.1		S
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, \text{ f} = 1 \text{ MHz}, V_{GS} = 0$		160		pF
Coss	Output Capacitance			27.5		pF
C _{rss}	Reverse Transfer Capacitance			4.7		pF

ELECTRICAL CHARACTERISTICS (CONTINUED)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on Delay Time	V _{DD} = 225 V, I _D = 0.5 A		6.7		ns
t _r	Rise Time	$R_G = 4.7\Omega V_{GS} = 10 V$ (see test circuit, Figure 3)		4		ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 360 \text{ V}, I_D = 1.5 \text{ A},$ $V_{GS} = 10 \text{ V}$		7 1.3 3.2	10	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{r(off)} t _f t _c	Off-voltage Rise Time Fall Time Cross-over Time			8.5 12 18		ns ns ns

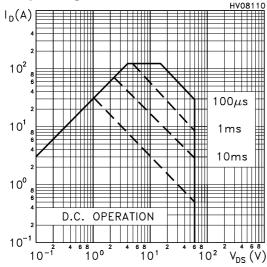
SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain Current				0.4	А
I _{SDM} (2)	Source-drain Current (pulsed)				1.6	А
V _{SD} (1)	Forward On Voltage	$I_{SD} = 0.4 \text{ A}, V_{GS} = 0$			1.6	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$\begin{split} I_{SD} &= 0.4 \text{ A, di/dt} = 100 \text{A/} \mu \text{s,} \\ V_{DD} &= 100 \text{ V, } T_{j} = 150^{\circ}\text{C} \\ (\text{see test circuit, Figure 5}) \end{split}$		225 530 4.7		ns nC A

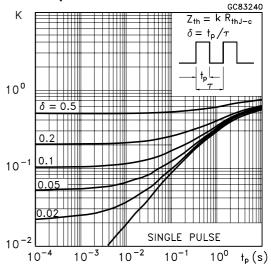
Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

2. Pulse width limited by safe operating area.

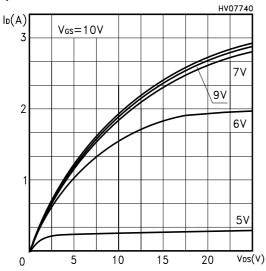
Safe Operating Area



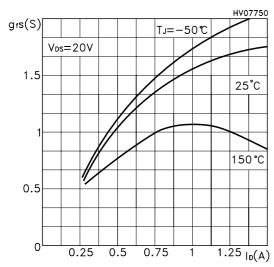
Thermal Impedance



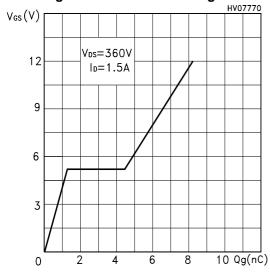
Output Characteristics

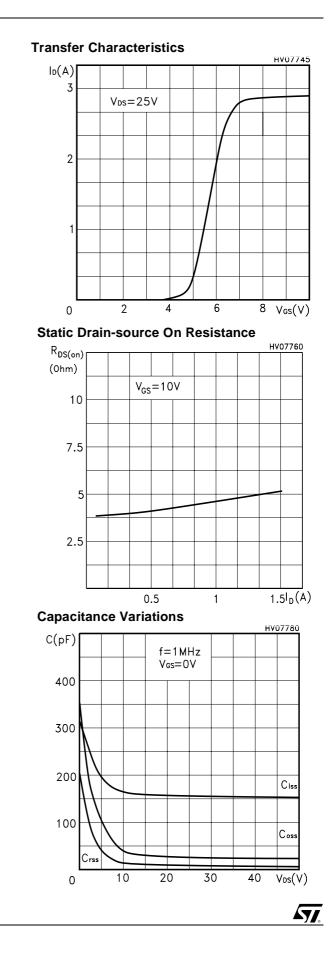


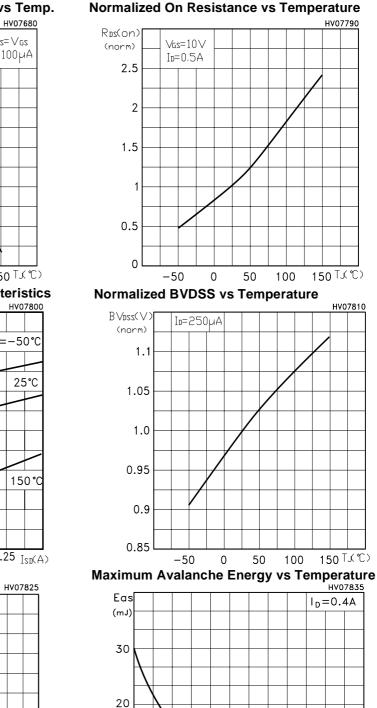
Transconductance



Gate Charge vs Gate-source Voltage







10

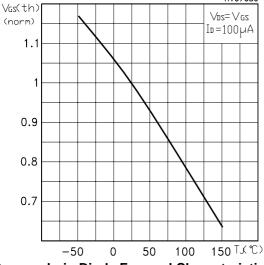
50

75

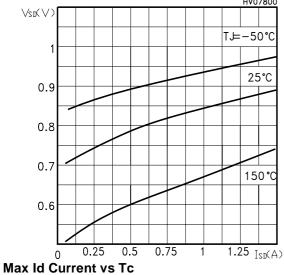
100

125

Normalized Gate Threshold Voltage vs Temp.



Source-drain Diode Forward Characteristics



HV07825 $I_{\alpha}(A)$ 0.5 0.4 0.3 0.2 0.1 0.2 0.1 0.2 0.1 0.2 0.1 0.2 0.1 0.5 0.5 0.1 0.5 0.2 0.1 0.2 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5

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150 ℃ ℃

Fig. 1: Unclamped Inductive Load Test Circuit

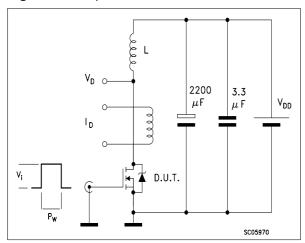


Fig. 3: Switching Times Test Circuit For Resistive Load

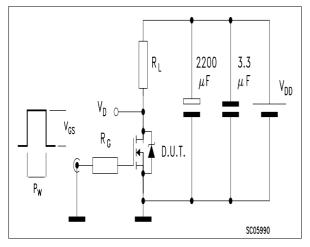


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

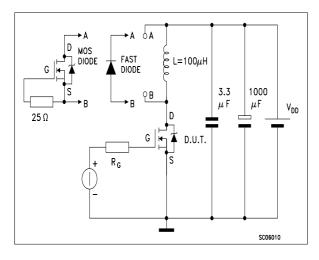


Fig. 2: Unclamped Inductive Waveform

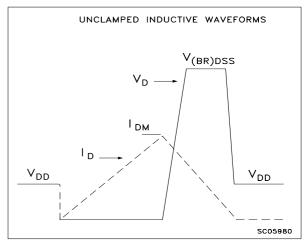
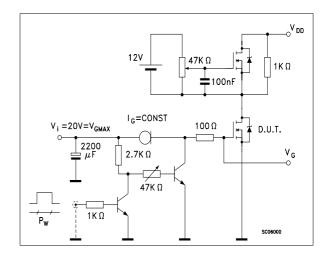
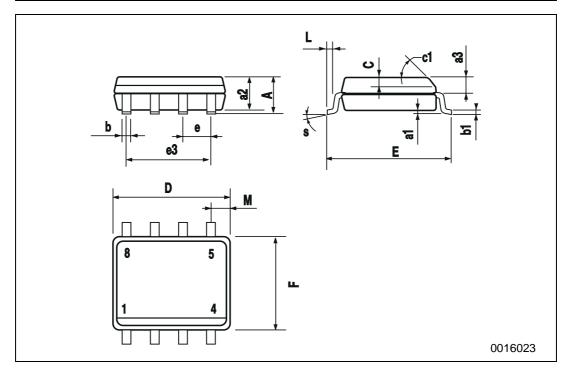


Fig. 4: Gate Charge test Circuit



mm			inch			
MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
		1.75			0.068	
0.1		0.25	0.003		0.009	
		1.65			0.064	
0.65		0.85	0.025		0.033	
0.35		0.48	0.013		0.018	
0.19		0.25	0.007		0.010	
0.25		0.5	0.010		0.019	
		45	(typ.)			
4.8		5.0	0.188		0.196	
5.8		6.2	0.228		0.244	
	1.27			0.050		
	3.81			0.150		
3.8		4.0	0.14		0.157	
0.4		1.27	0.015		0.050	
		0.6			0.023	
	0.1 0.65 0.35 0.19 0.25 4.8 5.8 3.8	MIN. TYP. 0.1	MIN. TYP. MAX. 1.75 1.75 0.1 0.25 1.65 0.85 0.65 0.85 0.35 0.48 0.19 0.25 0.25 0.5 4.8 5.0 5.8 6.2 1.27 3.81 3.8 4.0 0.4 1.27	MIN. TYP. MAX. MIN. 1.75 1.75 1.75 0.1 0.25 0.003 1.65 1.65 0.025 0.65 0.85 0.025 0.35 0.48 0.013 0.19 0.25 0.007 0.25 0.5 0.010 45 (typ.) 4.8 5.0 0.188 5.8 6.2 0.228 1.27 3.81 1.27 3.8 4.0 0.14 0.4 1.27 0.015	MIN. TYP. MAX. MIN. TYP. 1.75 1.	

SO-8 MECHANICAL DATA



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